

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BGA 5H1BN6 E6327	**Issued**	02. June 2021
MA#	MA001845962		
Package	PG-TSNP-6-10	**Weight***	0.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.093	11.17	11.17	111745	111745
bumps	non noble metal	copper	7440-50-8	0.007	0.82	0.82	8192	8192
leadframe	non noble metal	zinc	7440-66-6	0.001	0.08		758	
	non noble metal	tin	7440-31-5	0.001	0.09		947	
	non noble metal	chromium	7440-47-3	0.001	0.11		1137	
	non noble metal	copper	7440-50-8	0.313	37.61	37.89	376107	378949
encapsulation	organic material	carbon black	1333-86-4	0.001	0.10		954	
	plastics	epoxy resin	-	0.047	5.63		56320	
	inorganic material	silicondioxide	60676-86-0	0.350	42.01	47.74	420012	477286
leadfinish	non noble metal	tin	7440-31-5	0.017	2.07	2.07	20747	20747
solder	noble metal	silver	7440-22-4	0.000	0.01		70	
	non noble metal	tin	7440-31-5	0.002	0.29	0.30	2938	3008
ubm	non noble metal	titanium	7440-32-6	0.000			8	
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	65	73
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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